



Material Content Data Sheet



Sales Product Name		AIHD15N60R		Issued		20. July 2018		
MA#		MA001393172						
Package		PG-TO252-3-313		Weight*		318.03 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.995	0.63	0.63	6272	6272
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		463	
	non noble metal	copper	7440-50-8	147.096	46.25	46.31	462525	463127
	non noble metal	aluminium	7429-90-5	1.016	0.32	0.32	3195	3195
wire	non noble metal	aluminium	7429-90-5	1.016	0.32	0.32	3195	3195
encapsulation	organic material	carbon black	1333-86-4	1.412	0.44		4441	
	plastics	epoxy resin	-	24.714	7.77		77710	
	inorganic material	silicondioxide	60676-86-0	115.097	36.19	44.40	361909	444060
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11760	11760
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4467	4478
solder	non noble metal	tin	7440-31-5	0.043	0.01		135	
	noble metal	silver	7440-22-4	0.054	0.02		168	
	non noble metal	lead	7439-92-1	2.044	0.64	0.67	6426	6729
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60301	60379
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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